### PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
CHIH-LIN CHEN	06/19/2018
CHIN-CHOU LIU	07/03/2018
FONG-YUAN CHANG	06/19/2018
HUI-YU LEE	06/19/2018
PO-HSIANG HUANG	06/19/2018

#### **RECEIVING PARTY DATA**

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. VI, HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	16009579

#### **CORRESPONDENCE DATA**

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NAME OF SUBMITTER:	RANDY A. NORANBROCK
SIGNATURE:	/Randy A. Noranbrock/
DATE SIGNED:	08/14/2018

**Total Attachments: 1** 

PATENT REEL: 046799 FRAME: 0335

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PATENT REEL: 046799 FRAME: 0336



#### Docket No. T5057-1315 P20173159US00

## ASSIGNMENT

In consideration of the premises and other good	and valuable consideration	n in hand paid, i	he receipt and	sufficiency of
which is hereby acknowledged, the undersigned,		^ -	•	,

1) Chih-Lin CHEN

4) Hai-Yu LEE

2) Chin-Chou LIU

**RECORDED: 08/14/2018** 

5) Po-Hsiang HUANG

3) Fong-Yuan CHANG

who has made a certain new and useful invention, hereby sells, assigns and transfers unto <u>TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.</u>, having a place of business at No. 8, Li-Hsin Rd. VI. Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

300, Taiwan R.O.C.
its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, fitle and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

# INTEGRATED CIRCUIT, SEMICONDUCTOR DEVICE AND METHOD OF

MAI	NUFACTURING SAME
(a)	for which an application for United States Letters Patent was filed on $\frac{2018-06-15}{2018-06-15}$ , and identified by United States Patent Application No. $\frac{16/009,579}{2018-06-15}$ ; or
(b)	for which an application for United States Letters Patent was executed on,
all Un contin Proper	e undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and ited States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or uations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial ty to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:	
1) Chish- Sim Chen.	2018. Inne . 19.
Name: Chih-Lin CHEN	Date:
2) Chin-chou Ciu	2018.9.3
Name: Chin-Chon LIU	Date:
3) Forg-Tuen CHBN G	2018, 6, 19
Name: Fong-Yuan CHANG	Date:
4) Hai- yn Ler	2018.6.19.
Name: Hui-Yu LEE	Date:
s) Po-Harang HUANG	2012.6.69.
Name: Po-Hsing HUANG	Date:

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PATENT REEL: 046799 FRAME: 0337